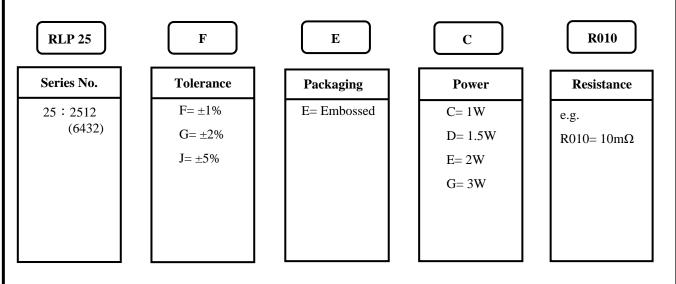


1. Scope

This specification applied to the products of current sensing resistor of metal plate for Lead-Free RLP series manufactured by TA-I TECHNOLOGY CO., LTD.

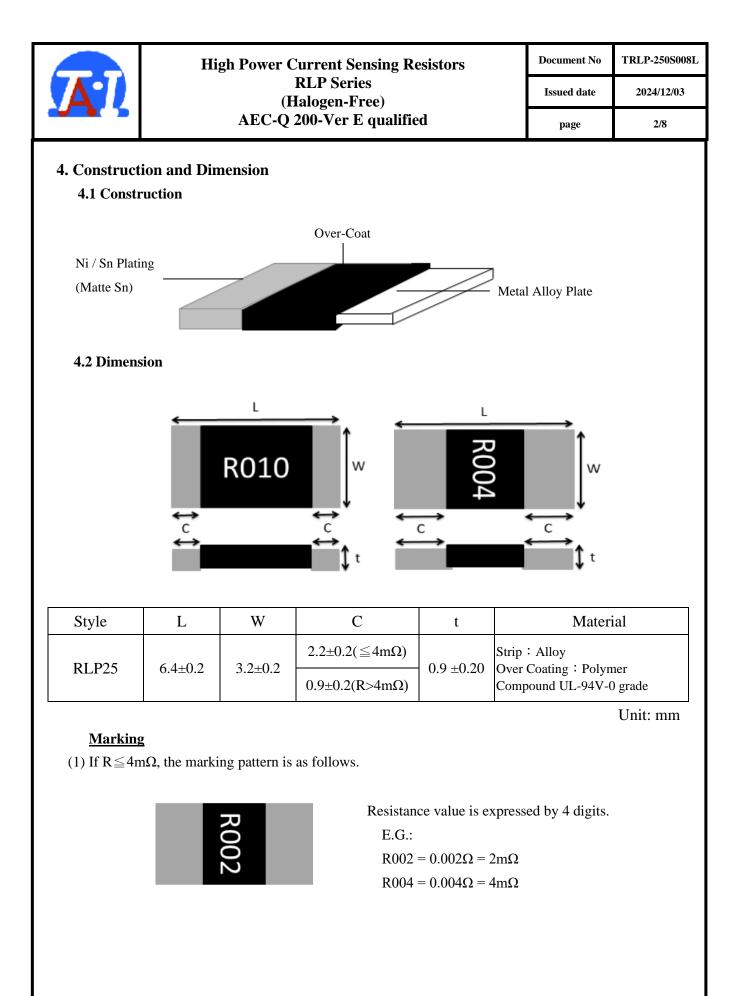
2. Type Designation



3. Features

Туре	RLP25	
Power Rating	$1m\Omega \leq R \leq 100m\Omega(1W \land 1.5 W \land 2 W \land 3W)$ $100 m\Omega < R \leq 680m\Omega(1W \land 1.5 W \land 2 W)$	
Resistance Value	$1m\Omega \leq R \leq 680m\Omega$	
Operation Temperature Range	-55°C~+170°C	
Temperature Coefficient of Resistance	±50ppm/°C	
Tolerance	$\pm 1\%, \pm 2\%, \pm 5\%$	
Insulation Resistance	100 Meg Ohms Minimum	
Maximum Working Current (A)	$(P/R)^{1/2}$	

*Note: The specifications and characteristics of this product are not suitable for series and parallel use.





(2) If R>4m Ω , the marking pattern is as follows.



Resistance value is expressed by 4 digits. E.G.: $R010 = 0.010\Omega = 10m\Omega$ $R020 = 0.020\Omega = 20m\Omega$

5. Reliability Tests:

Test Items	Reference	Condition of Test	Test Limits
Temperature Coefficient of Resistance	IEC60115-1 4.8	+25 ~ 125°C	Refer 3.0
High Temperature Exposure (Storage)	AEC-Q200-REV E-Test 3 MIL-STD202 Method 108	T=170°C,1000hrs, Measurement at 24hrs after test conclusion.	< ±(1%+0.0005Ω)
Temperature Cycling	AEC-Q200-REV E-Test 4 JESD22 Method JA-104	1000Cycle (-55°C to 155°C), Measurement at 24hrs after test conclusion.	$<\pm(0.5\%+0.0005\Omega)$
Short time overload	IEC60115-1 4.13	5 X rated power for 5s.	$< \pm (0.5\% + 0.0005\Omega)$
Biased Humidity	AEC-Q200-REV E-Test 7 MIL-STD-202 Method 103	10% Rated power at 85°C, RH:85% ,1000Hrs, Measurement at 24hrs after test conclusion.	$< \pm (0.5\% + 0.0005\Omega)$
Operation life	AEC-Q200-REV E-Test 8 MIL-STD-202 Method 108	1000 hours TA=70°C at 100% rated power. 90min ON and 30 min OFF. Measurement at 24±4 hours after test conclusion.	<±(1%+0.0005Ω)
External Visual	AEC-Q200-REV E-Test 9 MIL-STD-883 Method 2009	Electrical test not required. Inspect device construction, marking and workmanship.	
Physical Dimension	AEC-Q200-REV E-Test 10 JESD22 Method JB-100	Verify physical dimensions to the applicable device detail specification. Note: User(s) and Suppliers spec. Electrical test not required.	
Resistance to Solvents	AEC-Q200-REV E-Test 12 MIL-STD-202 Method 215	 a: Isopropyl Alcohol : Mineral Spirits = 1 : 3 b: Terpene Defluxer c: Deionized water : Propylene Glycol Monomethyl Ether : monoethanolamine = 42 : 1 : 1 	Marking and protective layer cannot be detached
Resistance to Soldering Heat	AEC-Q200-REV E-Test 15 MIL-STD-202 Method 210	T=260+/-5°C solder,10+/-1 sec dwell.	$<\pm(0.5\%\pm0.0005\Omega)$
Mechanical Shock	AEC-Q200-REV E-Test 13 MIL-STD-202 Method 213	100g's, Normal duration is 6ms, half sine shock pulse.	$<\pm(0.5\%\pm0.0005\Omega)$



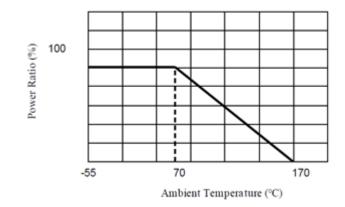
High Power Current Sensing Resistors RLP Series (Halogen-Free) AEC-Q 200-Ver E qualified

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Resistance to vibration	AEC-Q200-REV E-Test 14 MIL-STD-202 Method 204	5g's for 20min.12cycles, 10-2000Hz.	$< \pm (0.5\% + 0.0005\Omega)$
Board Flex	AEC-Q200-REV E-Test 21 AEC-Q200-005	Min 2mm deflection ,60sec.	$< \pm (0.5\% + 0.0005\Omega)$
Flammability	AEC-Q200-REV E-Test 20 UL-94	V-0 or V-1are acceptable, Electrical test not required.	V-0
ESD	AEC-Q200-REV E-Test 17 AEC-Q200-002 or ISO/DIS 10605	verify the voltage setting at 500V.	$< \pm (1\% + 0.0005\Omega)$
Solderability	AEC-Q200-REV E-Test 18 J-STD-002	aging 4 hours at 155 °C dry heat Lead-free solder bath at 235±3 °C Dipping time: 3±0.5 seconds.	> 95% area covered with tin
Terminal Strength (SMD)	AEC-Q200-REV E-Test 22 AEC-Q200-006	Force of 1.8kg for 60 seconds. Remarks: 0201-NA	$< \pm (1\% + 0.0005\Omega)$
Low Temperature Storage	EC60115-1 4.23.4 JIS C 5201-1 4.23.4	-55°C, 1000hrs	<±(1%+0.0005Ω)

5.1 Derating Curve



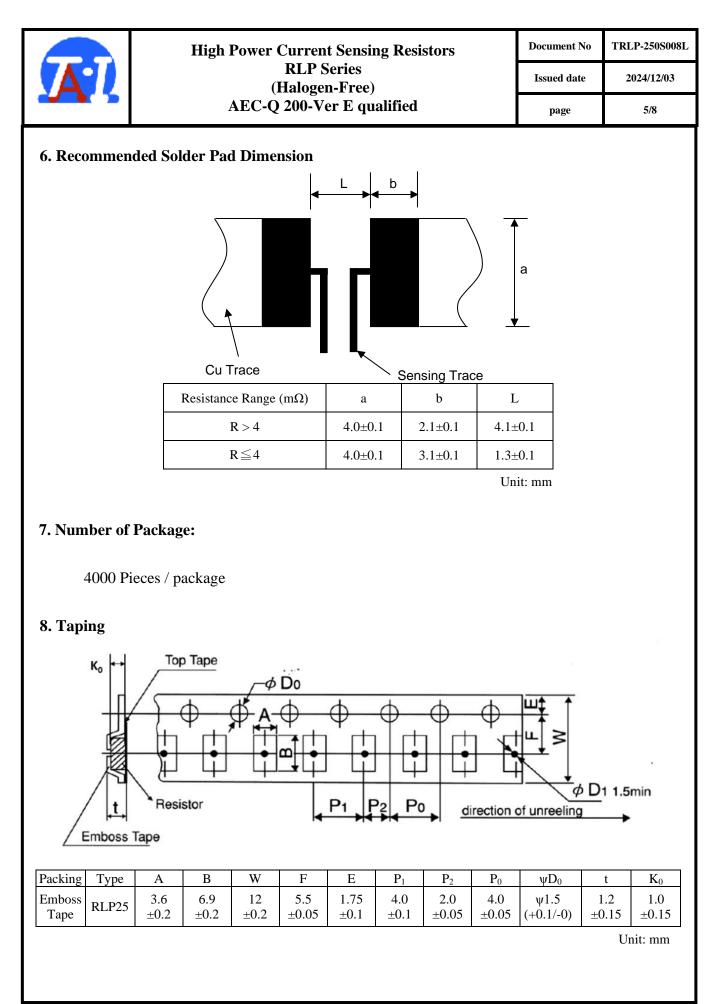
5.2 Rated Current

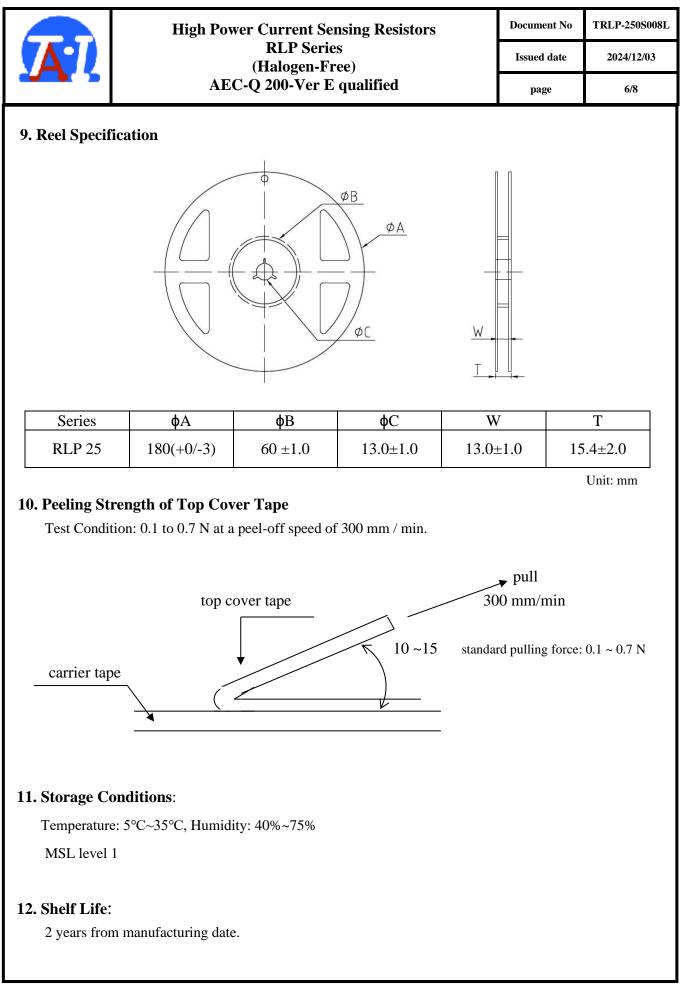
The rated current is calculated by the following Formula:

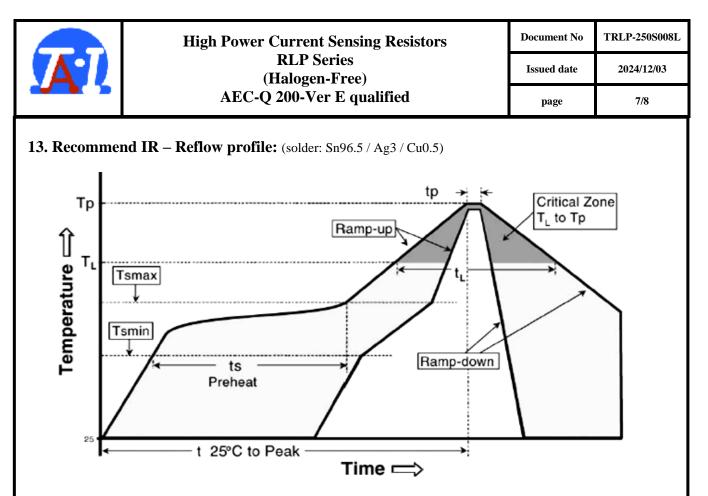
I: Rated Current (A)

$$I = \sqrt{P/R}$$

P: Rated Power (W)
R: Resistance Value (Ω)







Allowed Re-flow times: 3 times

Remark: To avoid discoloration phenomena of chip on terminal electrodes,

please use N2 Re-flow furnace.

Iron Solder:350±10°C, 3+1/-0 sec, 1 time

Profile Feature	Lead (Pb)-Free Assembly	
Average ramp-up rate (Tsmax to Tp)	3°C / second max.	
Preheat		
- Temperature Min (Ts _{min})	150°C	
- Temperature Max (Ts _{max})	200°C	
- Time (Ts _{min} to Ts _{max}) (ts)	(ts) 60 -120 seconds	
Time maintained above:		
- Temperature (T _L)	217°C	
- Time (T _L)	60-150 seconds	
Peak Temperature (Tp)	260°C	
Time within $^{+0}_{-5}$ °C of actual Peak	10 seconds	
Temperature (tp) ²		
Ramp-down Rate	6°C/second max.	
Time 25°C to Peak Temperature	8 minutes max.	



14. ECN

Engineering Change Notice: The customer will be informed with ECN if there is significant modification on the characteristics and materials described in approval sheet.

15. Manufacturing Country & City

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